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2010年4月1日  
瑞萨电子公司

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# H8/300L Super Low Power 系列

## 单精度浮点转换为带符号的 32 位 2 进制数

### 要点

将设定在通用寄存器中的单精度浮点转换为带符号的 32 位 2 进制数。

### 动作确认器件

H8/38024

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## 1. 参数

	内容	保存位置	数据长度 (字节)
输入	单精度浮点	R0、R1	4
输出	带符号的 32 位 2 进制数	R2、R3	4

## 2. 内部寄存器变化和标志变化

R0	R1
×	×
R2	R3
○	○
R4	R5
•	×
R6	R7
•	•

I	U	H	U
•	•	×	•
N	Z	V	C
×	×	×	×

•: 不变, ×: 不定, ○: 结果

## 3. 程序设计

	程序存储器 (字节)
	100
	数据存储器 (字节)
	0
	堆栈 (字节)
	0
	时钟周期数
	108
	重入
	可
	再定位
	可
	中途中断
	可

## 4. 注意事项

规格的时钟周期数是执行完图 27-1 时的值。

浮点格式请参照“关于单精度浮点<参考>”。

## 5. 说明

### 5.1 功能

(1) 参数的详细内容如下：

(a) 输入参数的设定

R0: 单精度浮点的高位 2 个字节

R1: 单精度浮点的低位 2 个字节

(b) 输出参数的设定

R2: 带符号的 32 位 2 进制数的高位 2 个字节

R3: 带符号的 32 位 2 进制数的低位 2 个字节

(2) 软件 FKTR 的执行例子如图 27-1 所示。

一旦如①设定输入参数，就如②将转换结果设定到 R2、R3。

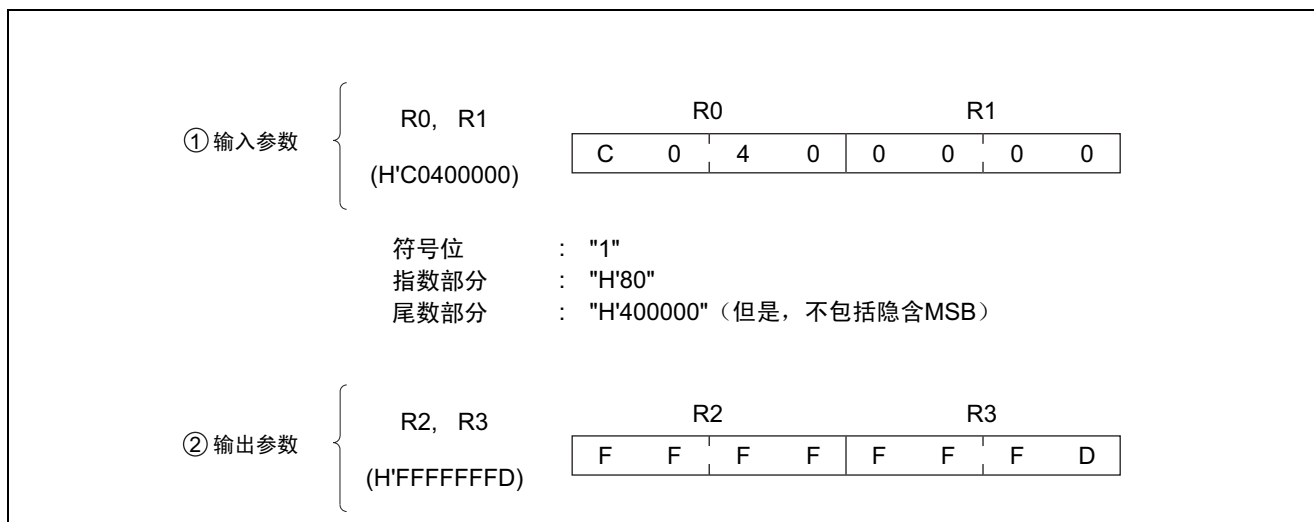


图 27-1 软件 FKTR 的执行例子

### 5.2 使用时的注意

(1) 单精度浮点是“0”或者小于|1|时，输出值为“0”。

(2) 单精度浮点大于等于 $2^{31}$ 时，输出值为同符号的最大值(H'7FFFFFFF 或者 H'80000000)。

(3) 执行软件 FKTR 后，设定在 R0、R1 的输入参数被破坏。如果执行后还需要输入参数，就必须预先保存到存储器。

### 5.3 数据存储器的说明

软件 FKTR 不使用数据存储器。

## 5.4 使用例

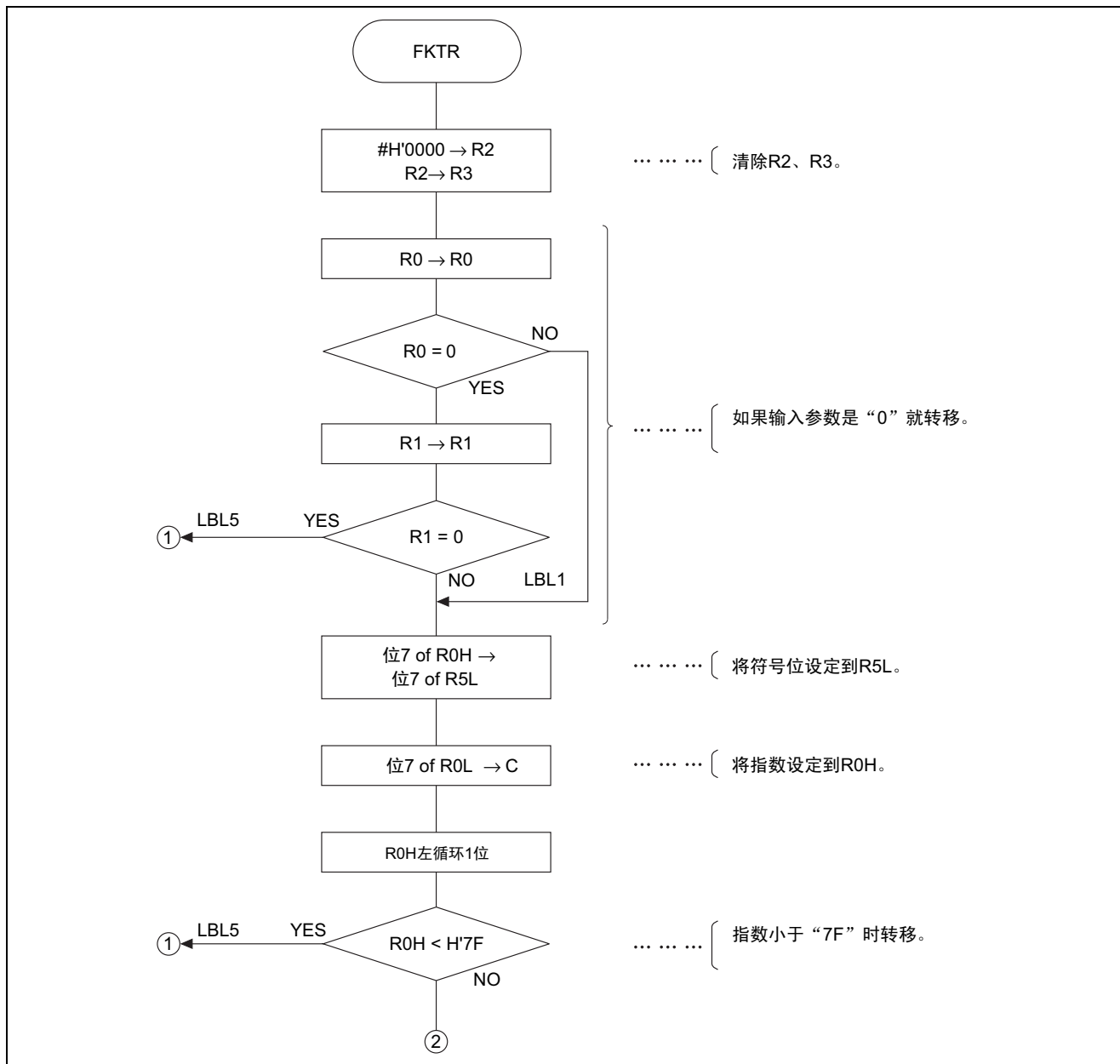
将单精度浮点设定到通用寄存器，子程序调用软件 FKTR

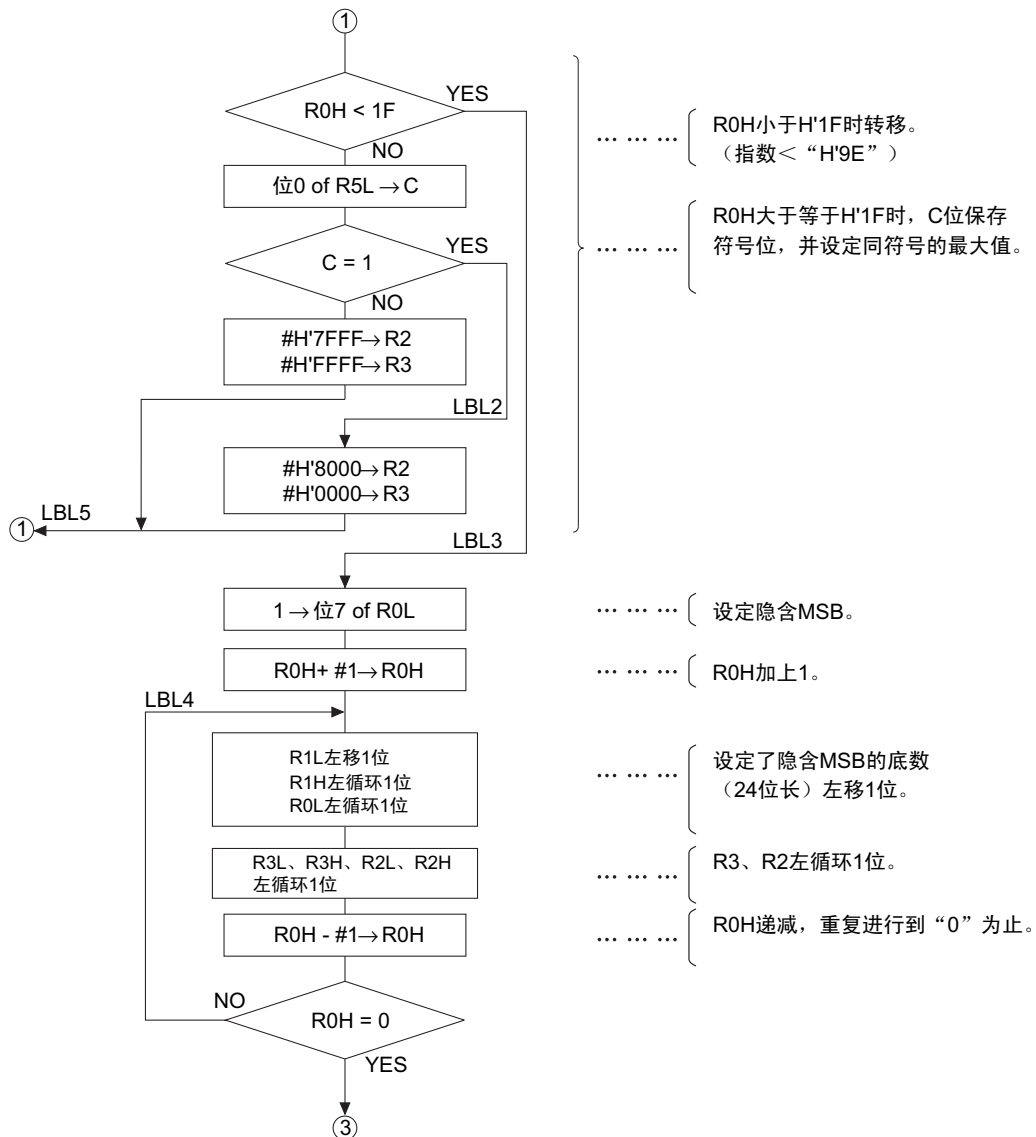
WORK1	. DATA. W	2, 0	...	...	确保用户程序设定单精度浮点的数据存储区。
WORK2	. DATA. W	2, 0	...	...	确保用户程序设定带符号32位2进制数的数据存储区。
	...				
	MOV. B	@WORK1, R0	...	...	将由户程序设定的单精度浮点
	MOV. W	@WORK1+2, R1	...	...	设定到输入参数。
	JSR	@FKTR	...	...	子程序调用软件FKTR。
	MOV. W	R2, @WORK2	...	...	将带符号32位2进制数设定到
	MOV. W	R3, @WORK2+2	...	...	输出参数。

## 5.5 工作原理

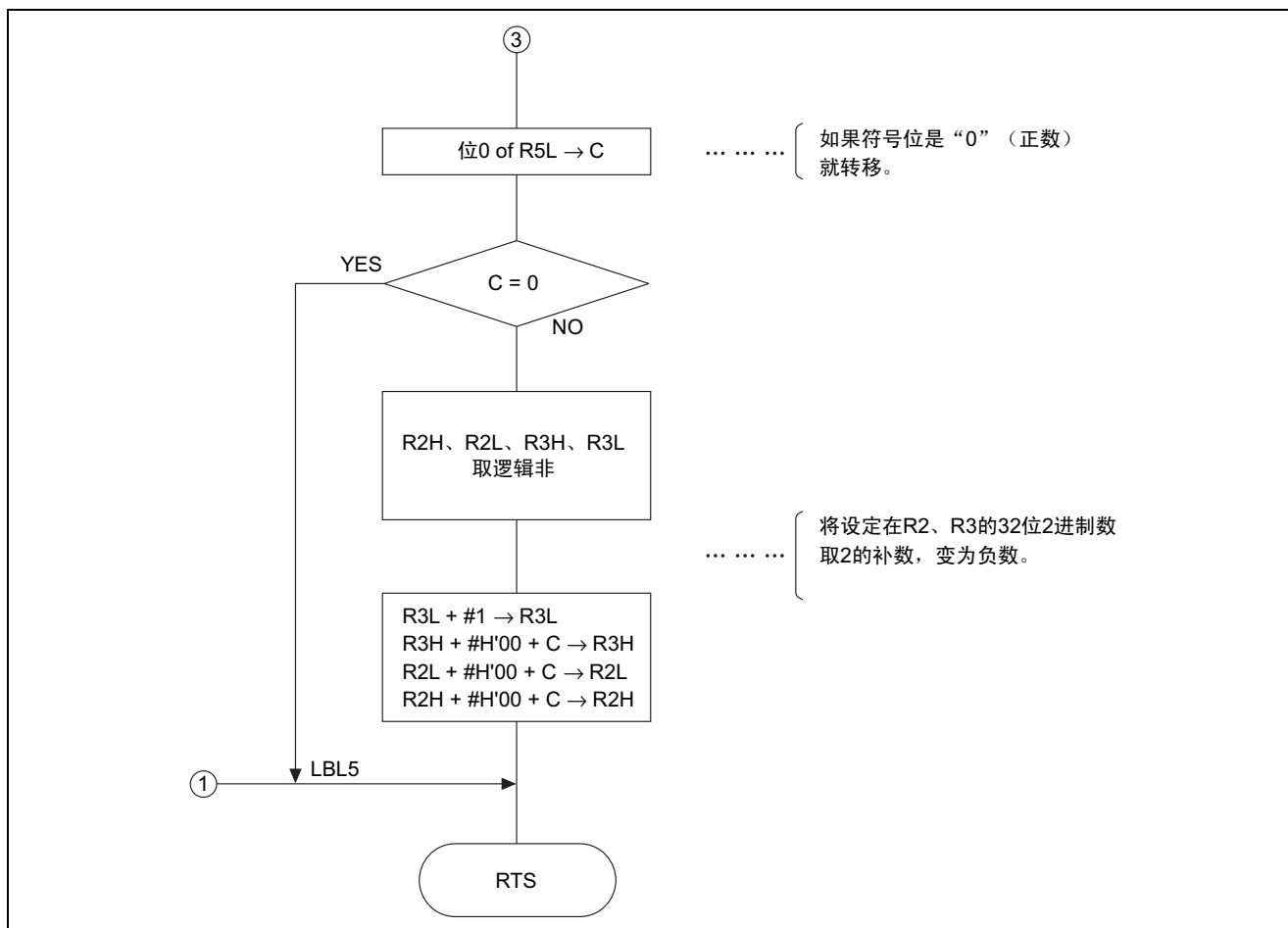
- (1) 在软件 FKTR 中，通过以下步骤将单精度浮点转换为带符号的 32 位 2 进制数：
- (2) 首先，判断输入参数：
  - (a) 如果输入参数是“0”，输出值就为“0”。
  - (b) 如果指数小于“H'7F”，输出值就为“0”。
  - (c) 如果指数大于等于“H'9E”，输出值就为同符号的最大值。
- (3) 其次，当输入参数不是“0”、绝对值大于等于“1”（指数为 H'7F）并且小于  $2^{31}$ （指数为 H'9E）时：
  - (a) 设定隐含 MSB。
  - (b) 将设定隐含 MSB 的尾数（24 位长）左移 1 位。
  - (c) R3、R2 左循环 1 位。
  - (d) 重复处理(b)、(c) “R0H + 1” 次。
  - (e) 如果符号位是负，就取 2 的补码，设定为负数。

## 6. 流程图









## 7. 程序清单

```

*** H8/300 ASSEMBLER      VER 1.0B **   08/18/92 10:17:31
PROGRAM NAME =

1          ;*****
2          ;*
3          ;*   00 - NAME           :CHANGE FLOATING POINT TO 32 BIT BINARY
4          ;*                               (FKTR)
5          ;*
6          ;*****
7          ;*
8          ;*   ENTRY              :R0 (UPPER WORD OF FLOATING POINT)
9          ;*                               R1 (LOWER WORD OF FLOATING POINT)
10         ;*
11         ;*   RETURNS            :R2      (UPPER WORD OF 32 BIT BINARY)
12         ;*                               R3      (LOWER WORD OF 32 BIT BINARY)
13         ;*
14         ;*****
15         ;
16 FKTR_cod C 0000          .SECTION          FKTR_code, CODE, ALIGN=2
17                               .EXPORT          FKTR
18         ;
19 FKTR_cod C      00000000 FKTR .EQU      $           ;Entry point
20 FKTR_cod C 0000 79020000 MOV.W      #H'0000,R2      ;Clear R2
21 FKTR_cod C 0004 0D23     MOV.W      R2,R3          ;Clear R3
22         ;
23 FKTR_cod C 0006 0D00     MOV.W      R0,R0
24 FKTR_cod C 0008 4604     BNE        LBL1
25 FKTR_cod C 000A 0D11     MOV.W      R1,R1
26 FKTR_cod C 000C 4754     BEQ        LBL5            ;Branch if R0=R1=0
27 FKTR_cod C 000E          LBL1
28 FKTR_cod C 000E 7770     BLD        #7,R0H
29 FKTR_cod C 0010 670D     BST        #0,R5L          ;Set sign bit to bit 0 of R5L
30 FKTR_cod C 0012 7778     BLD        #7,R0L
31 FKTR_cod C 0014 1200     ROTXL.B   R0H              ;Set exporment
32 FKTR_cod C 0016 F57F     MOV.B      #H'7F,R5H
33 FKTR_cod C 0018 1850     SUB.B      R5H,R0H
34 FKTR_cod C 001A 4546     BCS        LBL5            ;Branch if R0H<"H'7F"
35 FKTR_cod C 001C A01F     CMP.B      #H'1F,R0H
36 FKTR_cod C 001E 4518     BCS        LBL3            ;Branch if R0H<"H'1F"
37 FKTR_cod C 0020 770D     BLD        #0,R5L
38 FKTR_cod C 0022 450A     BCS        LBL2            ;Branch if sign bit = 1
39 FKTR_cod C 0024 79027FFF MOV.W      #H'7FFF,R2
40 FKTR_cod C 0028 7903FFFF MOV.W      #H'FFFF,R3      ;Set "H'7FFFFFFF"
41 FKTR_cod C 002C 4034     BRA        LBL5            ;Branch always
42 FKTR_cod C 002E          LBL2
43 FKTR_cod C 002E 79028000 MOV.W      #H'8000,R2
44 FKTR_cod C 0032 79030000 MOV.W      #H'0000,R3      ;Set "H'80000000"
45 FKTR_cod C 0036 402A     BRA        LBL5
46         ;
47 FKTR_cod C 0038          LBL3
48 FKTR_cod C 0038 7078     BSET       #7,R0L          ;Set implicit MSB
49 FKTR_cod C 003A 8001     ADD.B      #1,R0H          ;R0H + #1 -> R0H
50 FKTR_cod C 003C          LBL4
51 FKTR_cod C 003C 1009     SHLL.B    R1L              ;Shift mantissa 1 bit left
52 FKTR_cod C 003E 1201     ROTXL.B   R1H
53 FKTR_cod C 0040 1208     ROTXL.B   R0L

```

```

54                                     ;
55 FKTR_cod C 0042 120B             ROTXL.B R3L             ;Rotate 32 bit binary 1 bit left
56 FKTR_cod C 0044 1203             ROTXL.B R3H
57 FKTR_cod C 0046 120A             ROTXL.B R2L
58 FKTR_cod C 0048 1202             ROTXL.B R2H
59 FKTR_cod C 004A 1A00             DEC.B R0H             ;Decrement R0H
60 FKTR_cod C 004C 46EE             BNE LBL4             ;Branch if Z=0
61                                     ;
62 FKTR_cod C 004E 770D             BLD #0,R5L             ;Bit load sign bit to C flag
63 FKTR_cod C 0050 4410             BCC LBL5             ;Branch if C=0
64 FKTR_cod C 0052 1702             NOT R2H             ;2's complement 32 bit binary
65 FKTR_cod C 0054 170A             NOT R2L
66 FKTR_cod C 0056 1703             NOT R3H
67 FKTR_cod C 0058 170B             NOT R3L
68 FKTR_cod C 005A 8B01             ADD.B #H'01,R3L
69 FKTR_cod C 005C 9300             ADDX.B #H'00,R3H
70 FKTR_cod C 005E 9A00             ADDX.B #H'00,R2L
71 FKTR_cod C 0060 9200             ADDX.B #H'00,R2H
72 FKTR_cod C 0062 LBL5
73 FKTR_cod C 0062 5470             RTS
74                                     ;
75                                     .END
*****TOTAL ERRORS 0
*****TOTAL WARNINGS 0

```

修订记录

Rev.	发行日	修订内容	
		页	修订要点
1.00	2005.07.29	—	初版发行

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